

# HIGH DENSITY DESIGN COMPONENT SOLUTIONS

Preliminary Information

## General Description

### HIGH DENSITY DESIGN COMPONENT SOLUTIONS

NIC offers several component solutions to meet the needs of the next generation reduced size circuit designs.

#### Discrete component (capacitors / resistors / inductors / ferrite beads / thermistors)

- Sizes down to 0402 (0201 in development)

#### IPC - Integrated passive component arrays (resistors / capacitors / resistor-capacitor)

- Reduced sizes
- Reduces number of parts to be placed
- Lower assembly costs
- Reduced distance between components
- Improved high speed performance

